

1D Linear Sensor

FEATURES AND BENEFITS

- Operating magnetic field range: ± 50 mT
- Stable magnetic performance over temperature
- Linearity error: $\pm 0.5\%$ from -20 mT to $+20$ mT
- Differential outputs
- Supply voltage: 1.0 to 5.5 V
- Operating temperature: -40°C to 150°C
- Package options:
 - 6-lead SOT23
 - 6-lead DFN, $1.50\text{ mm} \times 1.50\text{ mm} \times 0.45\text{ mm}$
 - KGD (known good die) in wafer form

APPLICATIONS

- Linear measurements
- Proximity sensing
- Current sensing

DESCRIPTION

The CT100 is a 1D linear sensor in full-bridge configuration from Allegro developed on its patented XtremeSense™ TMR technology. The total magnetic field range for the CT100 is from -50 mT to 50 mT and it achieves a linearity error of $\pm 0.5\%$ for a range of -20 mT to 20 mT while providing XtremeSense performance to achieve unparalleled temperature stability across the full temperature range. The device supports a wide operating voltage range of 1.0 to 5.5 V.

The CT100 is available in a 6-lead SOT23 package, and for space-critical applications, a low-profile and small form factor 6-lead DFN package that is $1.50\text{ mm} \times 1.50\text{ mm} \times 0.45\text{ mm}$ in size. The CT100 is also available in die form where it will be shipped as unsawn wafers (wafer map files will be provided to indicate known good die).

FUNCTIONAL BLOCK DIAGRAMS

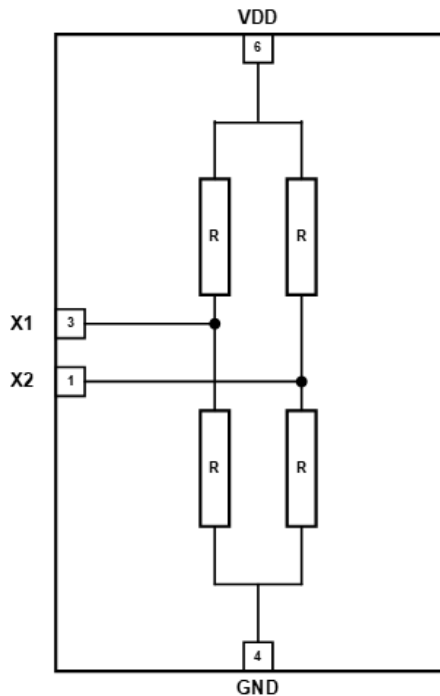


Figure 1: CT100 Functional Block Diagram for SOT23-6

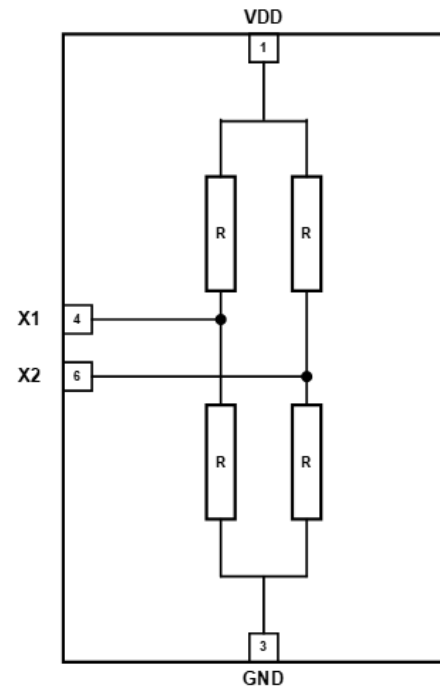


Figure 2: CT100 Functional Block Diagram for DFN-6

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SELECTION GUIDE

Part Number	Operating Temperature Range (°C)	Output Type	Package	Packing
CT100LW-IS6	-40 to 85	Differential	6-lead SOT23 2.90 mm × 2.80 mm × 1.20 mm	Tape and Reel
CT100LW-HS6	-40 to 125			
CT100LW-FS6	-40 to 150			
CT100LW-ID6	-40 to 85	Differential	6-lead DFN 1.50 mm × 1.50 mm × 0.45 mm	Tape and Reel
CT100LW-HD6	-40 to 125			
CT100LW-FD6	-40 to 150			
CT100LW-KGD	-40 to 150	Differential	Wafer Form	Unsawn Wafer

ABSOLUTE MAXIMUM RATINGS [1]

Characteristic	Symbol	Notes	Rating	Unit
Supply Voltage Strength	V _{DD}		-0.3 to 6.0	V
Analog Output Pins Maximum Voltage	V _{OUT}		±1560	mV
Electrostatic Discharge Protection Level	ESD	Human Body Model (HBM) per JESD22-A114	±4.0 (min)	kV
		Charged Device Model (CDM) per JESD22-C101	±1.0 (min)	kV
Maximum Magnetic Field	B _{MAX}	T _A = 25°C	±200	mT
Storage Temperature	T _{STG}		-65 to 160	°C
Lead Soldering Temperature	T _L	10 seconds	260	°C

[1] Stresses exceeding the absolute maximum ratings may damage the CT100 and may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

RECOMMENDED OPERATING CONDITIONS [1]

Characteristic	Symbol	Notes	Min.	Typ.	Max.	Unit
Supply Voltage Range	V _{DD}		1.0	3.0	5.5	V
Output Voltage Range	V _{OUT}		-1430	-	1430	mV
Operating Magnetic Field	B _{OP}		-	-	±50	mT
Operating Ambient Temperature	T _A	Industrial	-40	25	85	°C
		Extended Industrial	-40	25	125	°C
		Full Range	-40	25	150	°C

[1] The Recommended Operating Conditions table defines the conditions for actual operation of the CT100. Recommended operating conditions are specified to ensure optimal performance to the specifications. Allegro does not recommend exceeding them or designing to absolute maximum ratings.

PINOUT DIAGRAMS AND TERMINAL LISTS

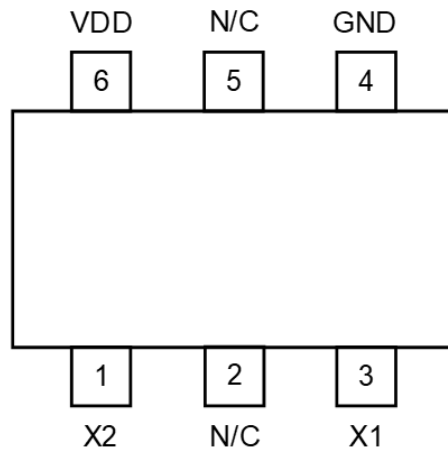


Figure 3: SOT23-6 Package, Top-Down View

Terminal List

Number	Name	Function
1	X2	Differential Output X2
2	N/C	No Connect
3	X1	Differential Output X1
4	GND	Ground
5	N/C	No Connect
6	VDD	Supply Voltage

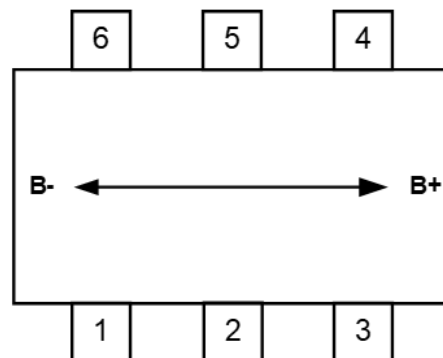


Figure 4: CT100 Axis of Sensitivity for SOT23-6 (Top Down View)

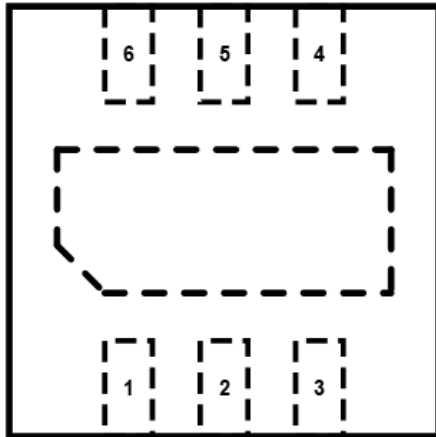


Figure 5: DFN-6, Top-Down View

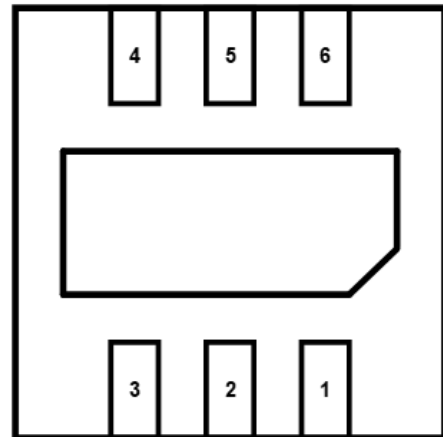


Figure 6: DFN-6, Bottom-Up View

Terminal List

Number	Name	Function
1	VDD	Supply Voltage
2	N/C	No Connect
3	GND	Ground
4	X1	Differential Output X1
5	N/C	No Connect
6	X2	Differential Output X2

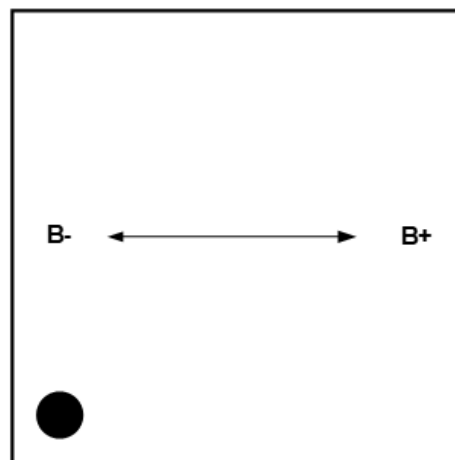


Figure 7: CT100 Axis of Sensitivity for DFN-6 (Top Down View)

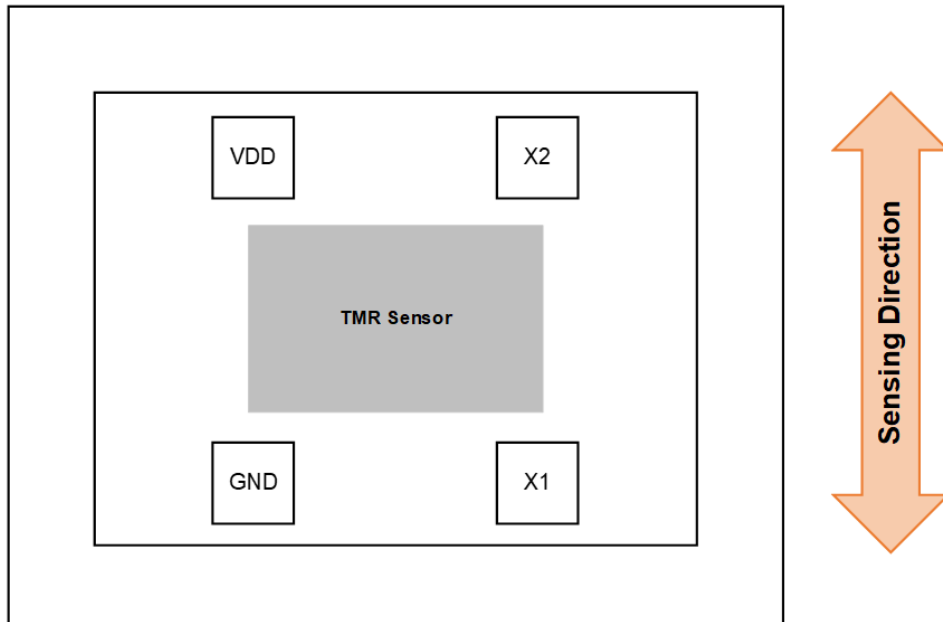


Figure 8: CT100 Die Layout and Axis of Sensitivity, Top-Down View

Pad List

Number	Name	Function
1	VDD	Supply Voltage
2	X2	Differential Output X2
3	X1	Differential Output X1
4	GND	Ground

ELECTRICAL CHARACTERISTICS: Valid for $V_{DD} = 1.0\text{ V}$ to 5.5 V and $T_A = -40^\circ\text{C}$ to 150°C , typical values are $V_{DD} = 3.0\text{ V}$ and $T_A = 25^\circ\text{C}$, unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
MAGNETIC						
Operating Magnetic Field	B_{OP}		–	–	± 50	mT
ELECTRICAL						
Bridge Resistance	R_{BRIDGE}		20	–	40	k Ω
Power Consumption	P_D	$V_{DD} = 3.0\text{ V}$, $R_{BRIDGE} = 30\text{ k}\Omega$	–	0.30	–	mW
Offset Voltage	V_{OFFSET}	$B_{OP} = \pm 20\text{ mT}$	–5		+5	mV/V
Sensitivity (Full-Bridge Gain)	S	$B_{OP} = \pm 20\text{ mT}$	3.8	4.5	5.2	mV/V/mT
Bridge Temperature Coefficient Resistance [1]	TCR_{BRIDGE}		–	–	–750	ppm/ $^\circ\text{C}$
Offset Voltage Temperature Coefficient [1]	TCO		–	–	± 4.0	$\mu\text{V/V}/^\circ\text{C}$
Sensitivity Temperature Coefficient [1]	TCS		–	–250	–350	ppm/ $^\circ\text{C}$
Linearity	L	$B_{OP} = \pm 20\text{ mT}$	–	–	± 0.5	%
Hysteresis Error	E_{HYST}	$B_{OP} = \pm 20\text{ mT}$, $T_A = 25^\circ\text{C}$	–	–	0.05	%
Output Noise [1]	e_N	$f = 10\text{ Hz}$, $V_{DD} = 1.0\text{ V}$, $B_{OP} = 0\text{ mT}$, $T_A = 25^\circ\text{C}$	–	700	–	$\text{nV}_{RMS}/\sqrt{\text{Hz}}$

[1] Guaranteed by design and characterization; not tested in production.

ELECTRICAL CHARACTERISTICS

$V_{DD} = 1.0\text{ V}$ and $T_A = 25^\circ\text{C}$ (unless otherwise specified)

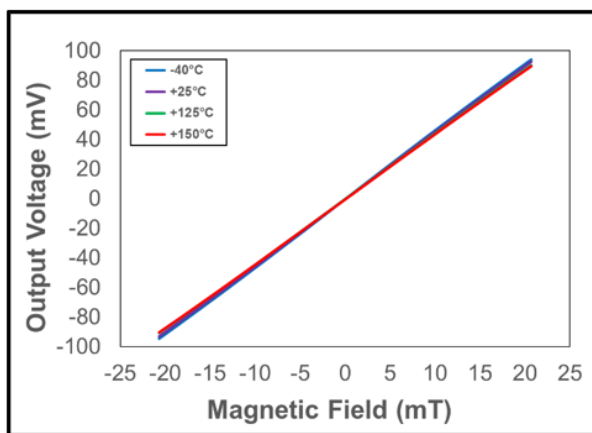


Figure 9: Sensitivity – Output Voltage vs. Magnetic Field vs. Temperature

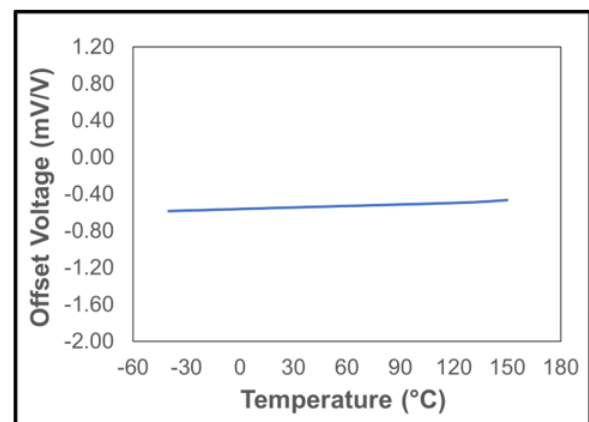


Figure 10: Offset Voltage vs. Temperature

RECOMMENDED APPLICATION CIRCUIT

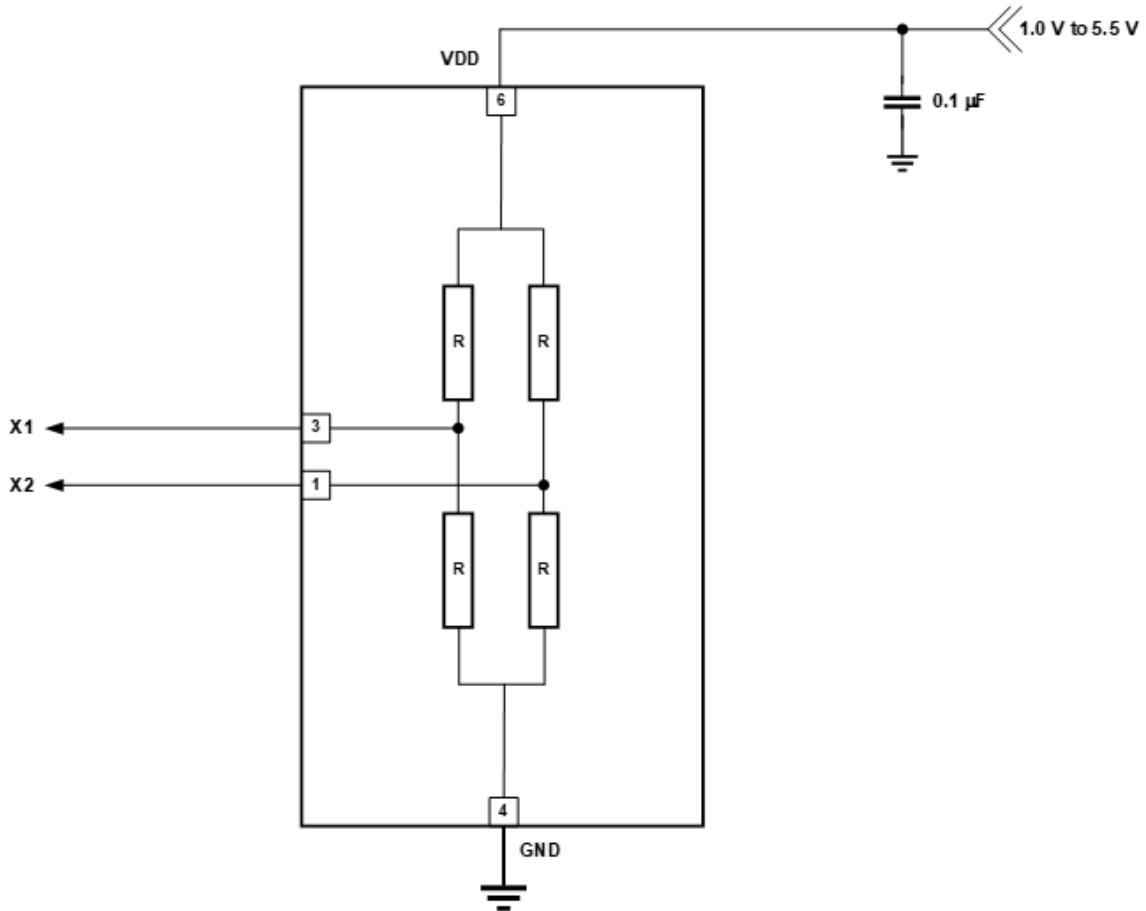


Figure 11: CT100 (SOT23-6) Application Diagram

Table 1: Recommended External Components

Component	Description	Vendor and Part Number	Parameter	Min.	Typ.	Max.	Unit
C _{BYP}	0.1 μF, X7R	Murata GRM033Z71A104KE14	C	–	0.1	–	μF

Applications Information

The XtremeSense TMR sensor location for the CT100 for the x, y dimensions are shown in Figure 12 and Figure 13 for the SOT23-6 and DFN-6 packages, respectively. Figure 14 and Figure 15 illustrates the location of the CT100 XtremeSense TMR sensor from the z dimension. All dimensions in the figures below are nominal.

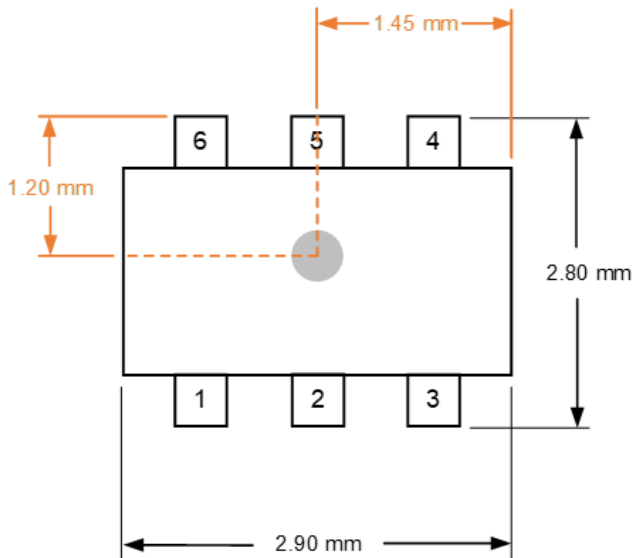


Figure 12: XtremeSense TMR Sensor Location in x-y Plane for CT100 in SOT23-6 Package

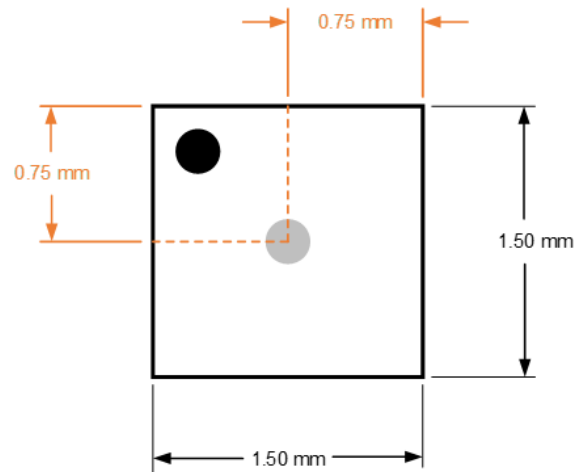


Figure 13: XtremeSense TMR Sensor Location in x-y Plane for CT100 in DFN-6 Package

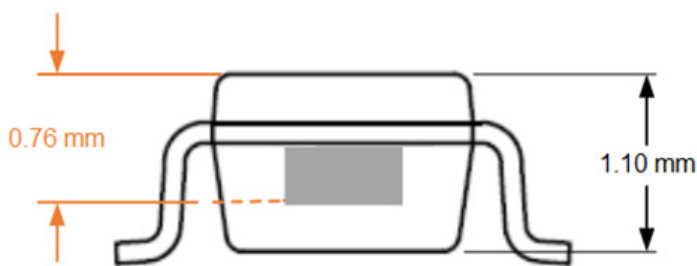


Figure 14: XtremeSense TMR Sensor Location in z Dimension for CT100 in SOT23-6 Package



Figure 15: XtremeSense TMR Sensor Location in z Dimension for CT100 in DFN-6 Package

PACKAGE OUTLINE DRAWINGS

For Reference Only – Not for Tooling Use

Dimensions in millimeters – NOT TO SCALE

Dimensions exclusive of mold flash, gate burs, and dambar protrusions

Exact case and lead configuration at supplier discretion within limits shown

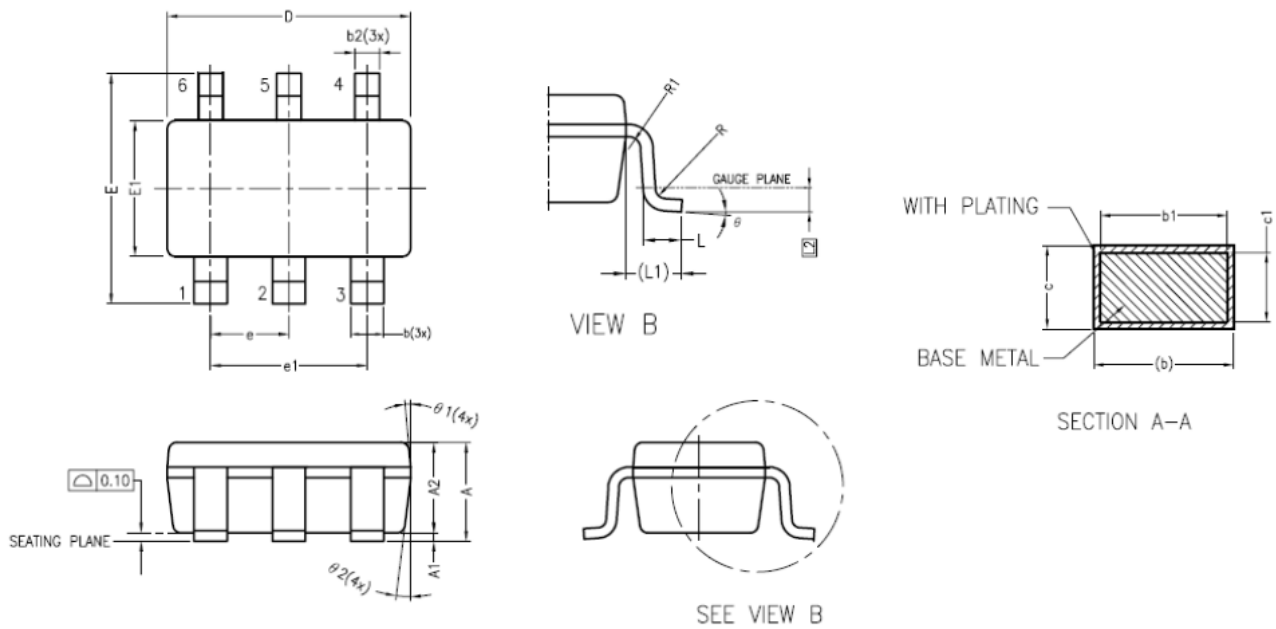


Figure 16: 6-Lead SOT23 Package Drawing

Table 2: CT100 6-Lead SOT23 Package Dimensions

Symbol	Dimensions in Millimeters (mm)		
	Min.	Typ.	Max.
A	1.05	1.20	1.35
A1	0.00	0.10	0.15
A2	1.00	1.10	1.20
b	0.40	–	0.50
b1	0.40	–	0.45
b2	0.30	–	0.40
c	0.08	–	0.22
c1	0.08	0.13	0.20
D	2.80	2.90	3.00
E	2.60	2.80	3.00
E1	1.50	1.60	1.70

Symbol	Dimensions in Millimeters (mm)		
	Min.	Typ.	Max.
e	0.95 BSC		
e1	1.90 BSC		
L	0.35	0.43	0.60
L1	0.60 REF		
L2	0.25 BSC		
R	0.10	–	–
R1	0.10	–	0.25
theta	0°	4°	8°
theta1	5°	6°	15°
theta2	5°	8°	15°

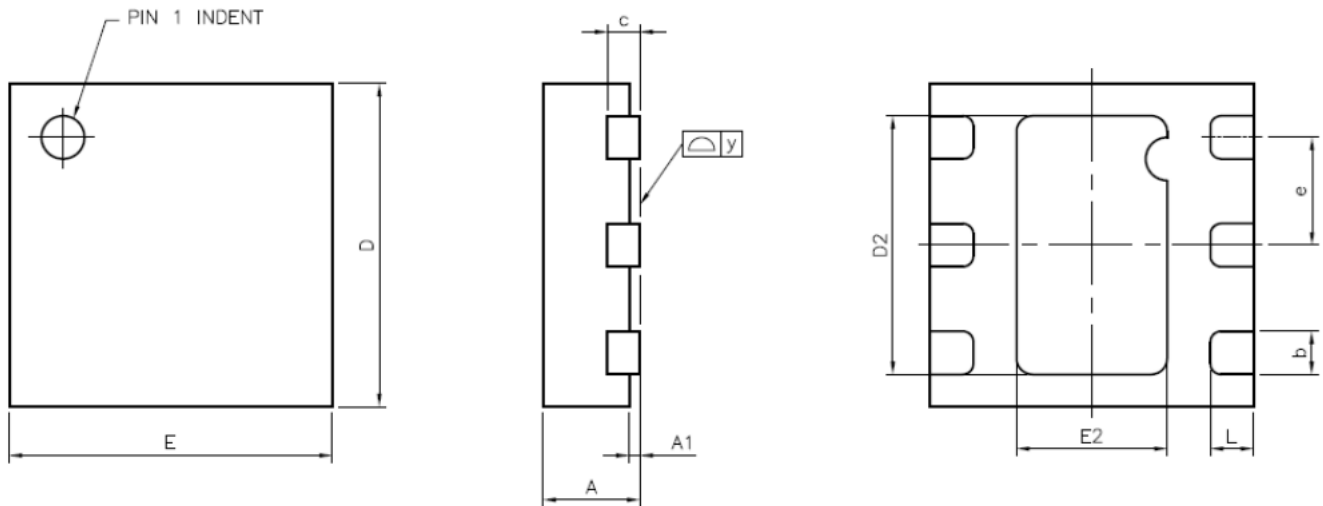


Figure 17: DFN-6 Package Drawing

Table 3: CT100 DFN-6 Package Dimensions

Symbol	Dimensions in Millimeters (mm)		
	Min.	Typ.	Max.
A	0.40	0.45	0.50
A1	0.00	0.02	0.05
b	0.15	0.20	0.25
c	–	0.15 REF	–
D	1.40	1.50	1.60
D2	1.15	1.20	1.25
E	1.40	1.50	1.60
E2	0.65	0.70	0.75
e	–	0.50	–
L	0.15	0.20	0.25
y	0.000	–	0.075

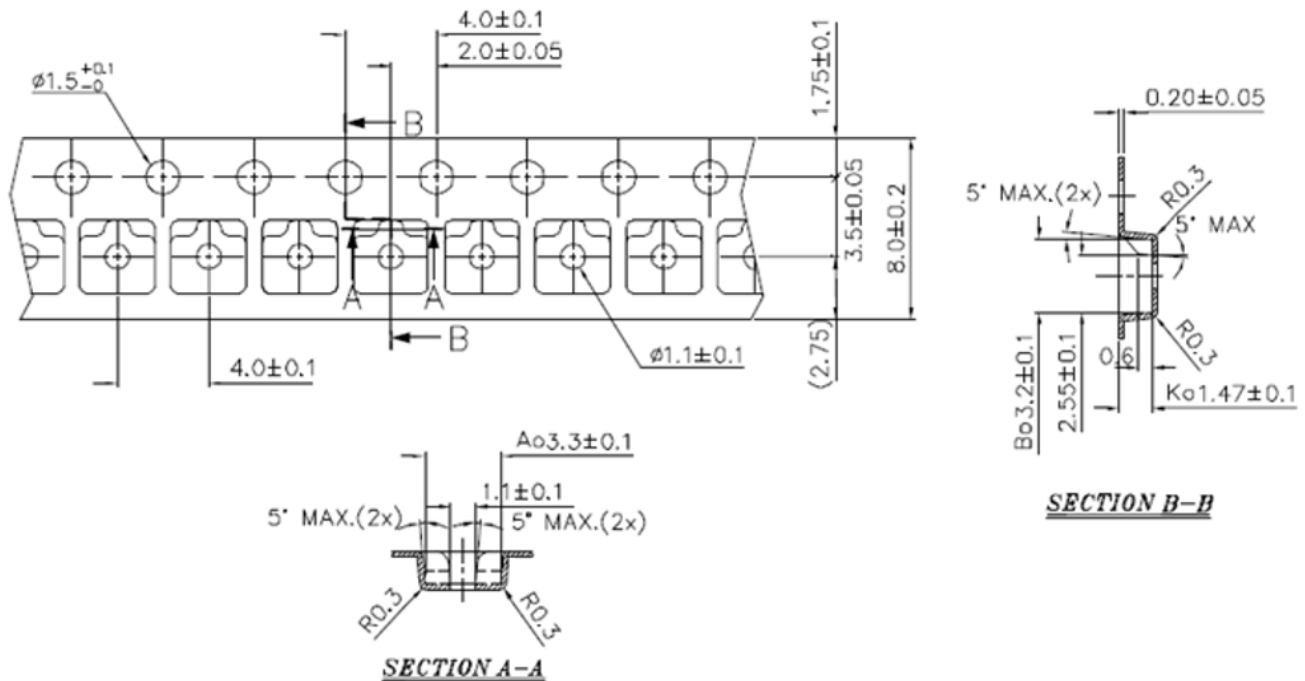
TAPE AND REEL POCKET DRAWINGS AND DIMENSIONS

For Reference Only – Not for Tooling Use

Dimensions in millimeters – NOT TO SCALE

Dimensions exclusive of mold flash, gate burs, and dambar protrusions

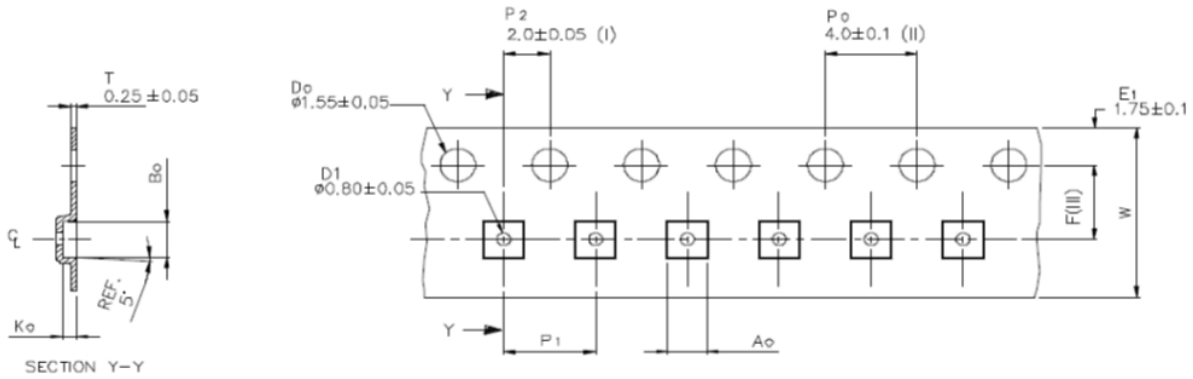
Exact case and lead configuration at supplier discretion within limits shown



NOTES:

1. Material: Conductive Polystyrene.
2. Dimensions in mm.
3. 10 sprocket hole pitch cumulative tolerance ± 0.20 mm.
4. Camber not to exceed 1 mm in 100 mm.
5. Pocket position relative to sprocket hole measured as true position of pocket and not pocket hole.
6. (S.R. Ω/sq) means surface electric resistivity of the carrier tape.

Figure 18: Tape and Pocket Drawing for SOT23 Package



NOTES:

1. Measured from centerline of sprocket hole to centerline of pocket.
2. Cumulative tolerance of 10 sprocket holes is ± 0.20 .
3. Measured from centerline of sprocket hole to centerline of pocket.
4. Other material available.

Figure 19: Tape and Pocket Drawing for DFN-6 Package

Table 4: DFN-6 Tape and Pocket Dimensions

Symbol	Dimension (mm)
Ao	1.70 ± 0.05
Bo	1.70 ± 0.05
Ko	0.60 ± 0.05
F	3.50 ± 0.05
P1	4.00 ± 0.10
DW	8.00 ± 0.30

PACKAGE INFORMATION

Table 5: CT100 Package Information

Part Number	Package Type	# of Leads	Package Quantity	Lead Finish	Eco Plan [1]	MSL Rating [2]	Operating Temperature [3]	Device Marking [4]
CT100LW-IS6	SOT23	6	3000	Sn	Green & RoHS	1	-40°C to 85°C	CT YWWS
CT100LW-HS6	SOT23	6	3000	Sn	Green & RoHS	1	-40°C to 125°C	CT YWWS
CT100LW-FS6	SOT23	6	3000	Sn	Green & RoHS	1	-40°C to 150°C	CT YWWS
CT100LW-ID6	DFN	6	3000	Sn	Green & RoHS	1	-40°C to 85°C	C YZ
CT100LW-HD6	DFN	6	3000	Sn	Green & RoHS	1	-40°C to 125°C	C YZ
CT100LW-FD6	DFN	6	3000	Sn	Green & RoHS	1	-40°C to 150°C	C YZ

[1] RoHS is defined as semiconductor products that are compliant to the current EU RoHS requirements. It also will meet the requirement that RoHS substances do not exceed 0.1% by weight in homogeneous materials. Green is defined as the content of chlorine (Cl), bromine (Br), and antimony trioxide based flame retardants satisfy JS709B low halogen requirements of $\leq 1,000$ ppm.

[2] MSL Rating = Moisture Sensitivity Level Rating as defined by JEDEC standard classifications.

[3] Package will withstand ambient temperature range of -40°C to 150°C and storage temperature range of -65°C to 160°C.

[4] Device Marking for SOT23 is defined as XZ YWWS where XZ = part number, Y = year, WW = work week, and S = sequential number. DFN is defined as X where X = part number and YZ = date code information.

Revision History

Number	Date	Description
3	November 2, 2023	Document rebranded and minor editorial updates
4	June 4, 2024	Added notes to package outline drawing (pages 9 and 11)

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